

US30KBV80FR

Bridge Diodes

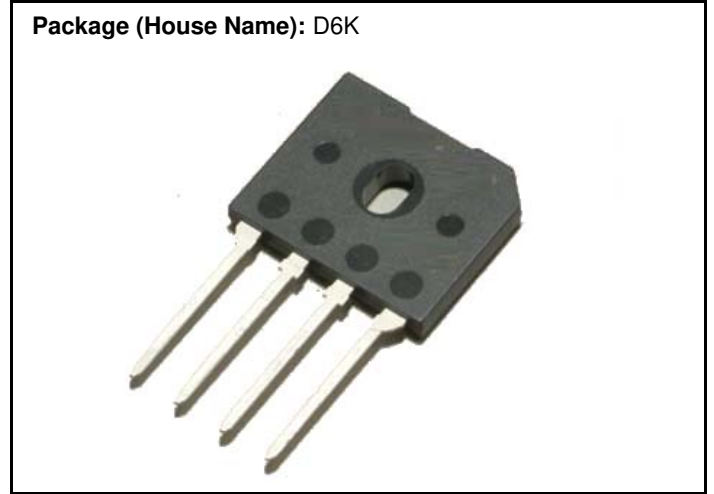
800V, 30A

Feature

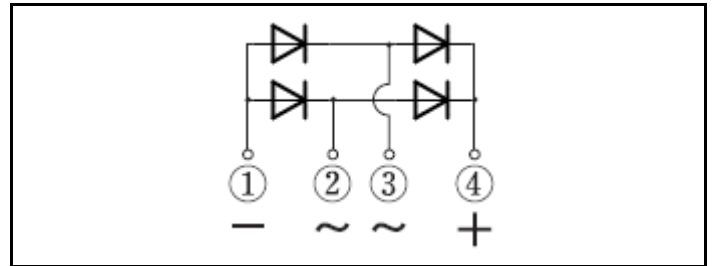
- Small・Compact SIP
- UL E142422
- Halogen free
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): D6K



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T _{stg}		-55 to 175	°C
Junction temperature	T _j		-55 to 175	°C
Repetitive peak reverse voltage	V _{RRM}		800	V
Average forward current	I _{F(AV)}	60Hz sine wave, Resistance load, With heatsink, T _c =126°C	30	A
Average forward current	I _{F(AV)}	60Hz sine wave, Resistance load, On glass-epoxy substrate, T _a =25°C ※	2.8	A
Surge forward current	I _{FSM}	60Hz sine wave, Non-repetitive 1 cycle peak value, T _j =25°C	350	A
Surge forward current	I _{FSM1}	t _p =1ms, sine wave, Non-repetitive, peak value, per diode, T _j =25°C	1010	A
Current squared time	I ² t	1ms ≤ t _p < 8.3ms, T _j =25°C, per diode	510	A ² s
Dielectric strength	V _{dis}	Terminals to case, AC 1 minute	2	kV
Mounting torque	TOR	(Recommended torque : 0.5N·m)	0.8	N·m

※ : See the original Specifications

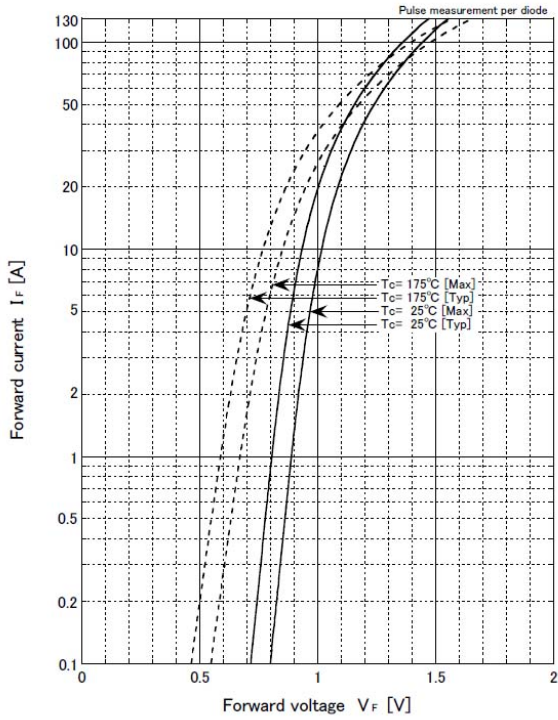
Electrical Characteristics (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V _F	I _F =15A, Pulse measurement, per diode			1.05	V
Reverse current	I _R	V _R =800V, Pulse measurement, per diode			5	μA
Thermal resistance	R _{th(j-c)}	Junction to case, With heatsink			0.8	°C/W
Thermal resistance	R _{th(j-l)}	Junction to lead, On glass-epoxy substrate ※			5	°C/W
Thermal resistance	R _{th(j-a)}	Junction to ambient, On glass-epoxy substrate ※			35	°C/W

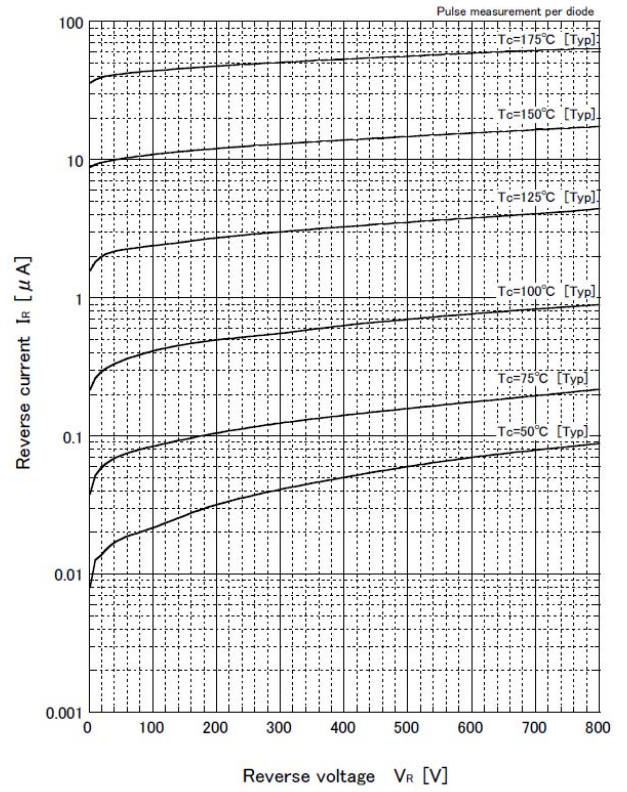
* :See the original Specifications

CHARACTERISTIC DIAGRAMS

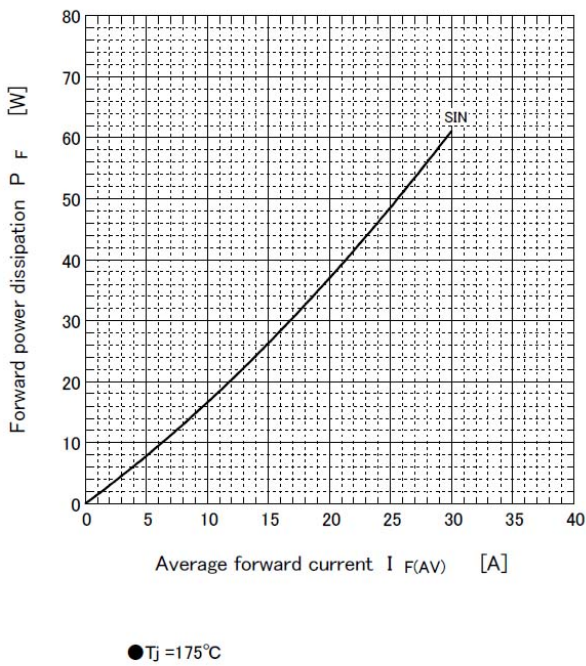
Forward voltage



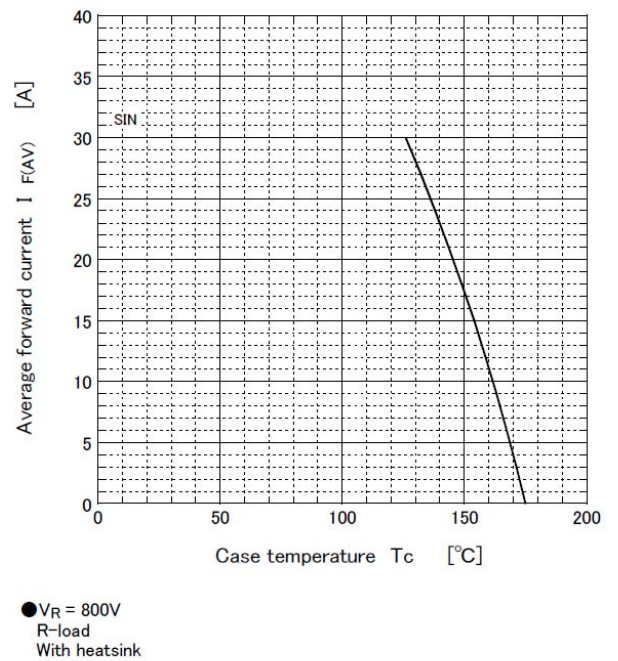
Reverse current



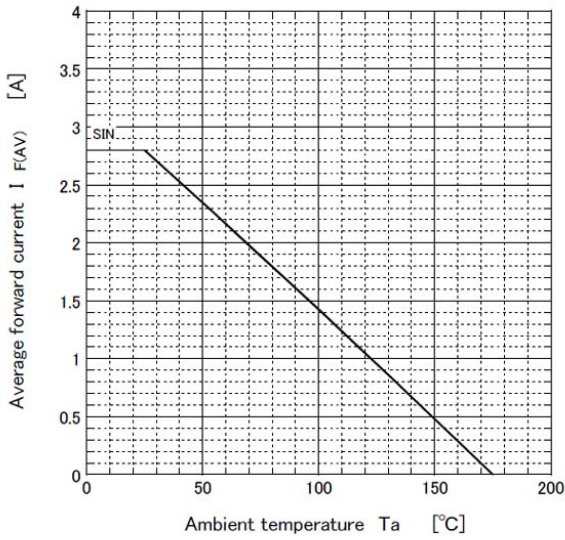
Forward power dissipation



Derating curve



Derating curve

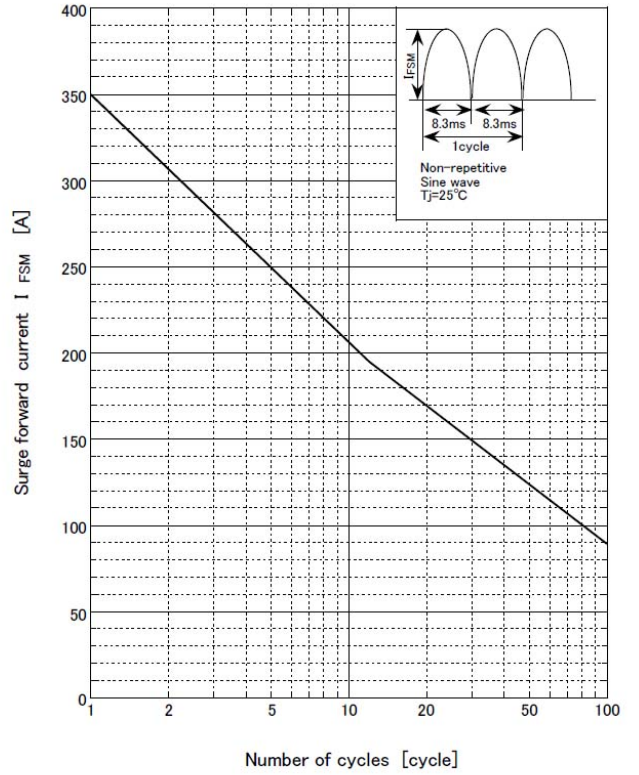


● $V_R = 800V$
R-load
Free in air

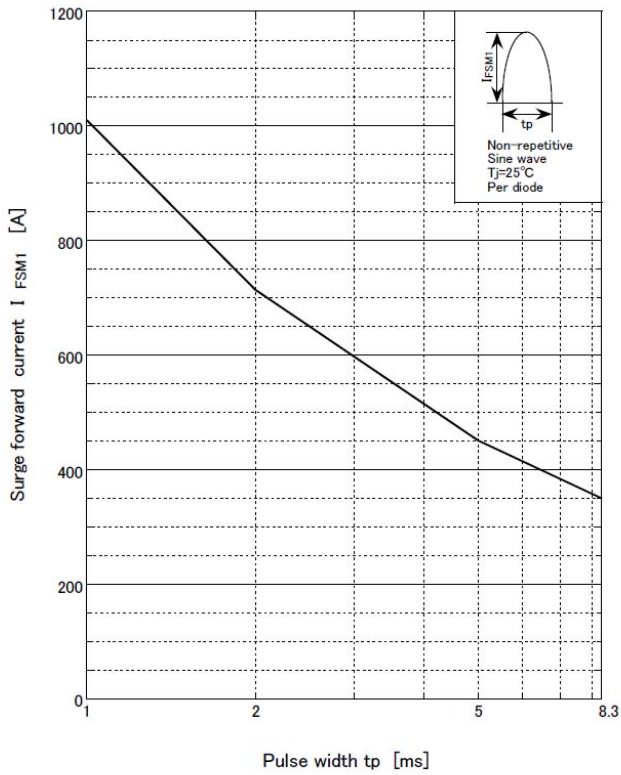
● Substrate detail

Type	Glass-epoxy
Size	90mm × 150mm
Thickness	1mm
Conductor thickness	35 μm
Pattern area	160mm ²

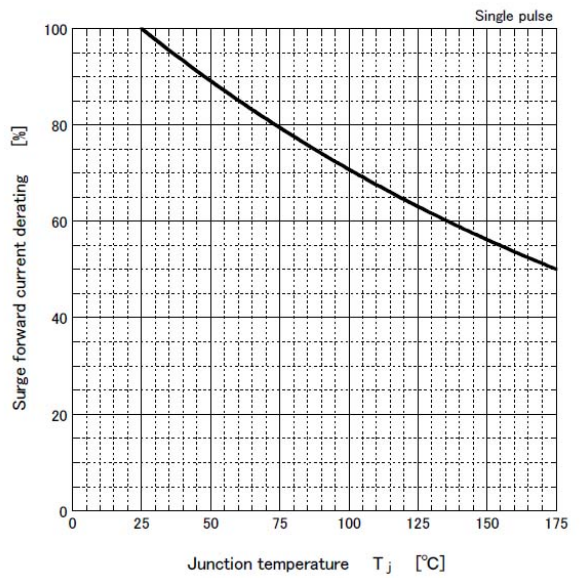
Surge forward current capability



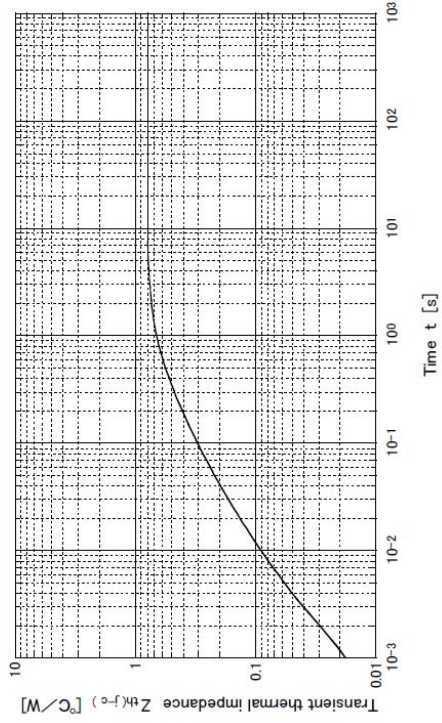
Surge forward current capability



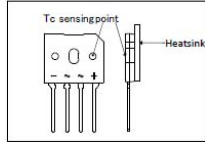
Surge forward current derating vs Junction temperature



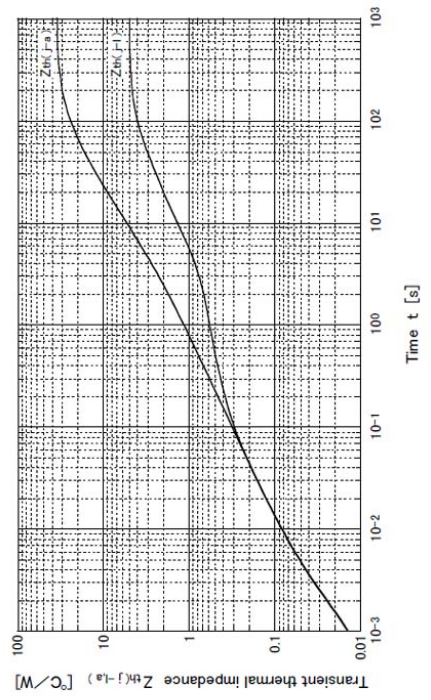
Transient thermal impedance



● Tc sensing point



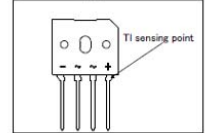
Transient thermal impedance



● Substrate detail

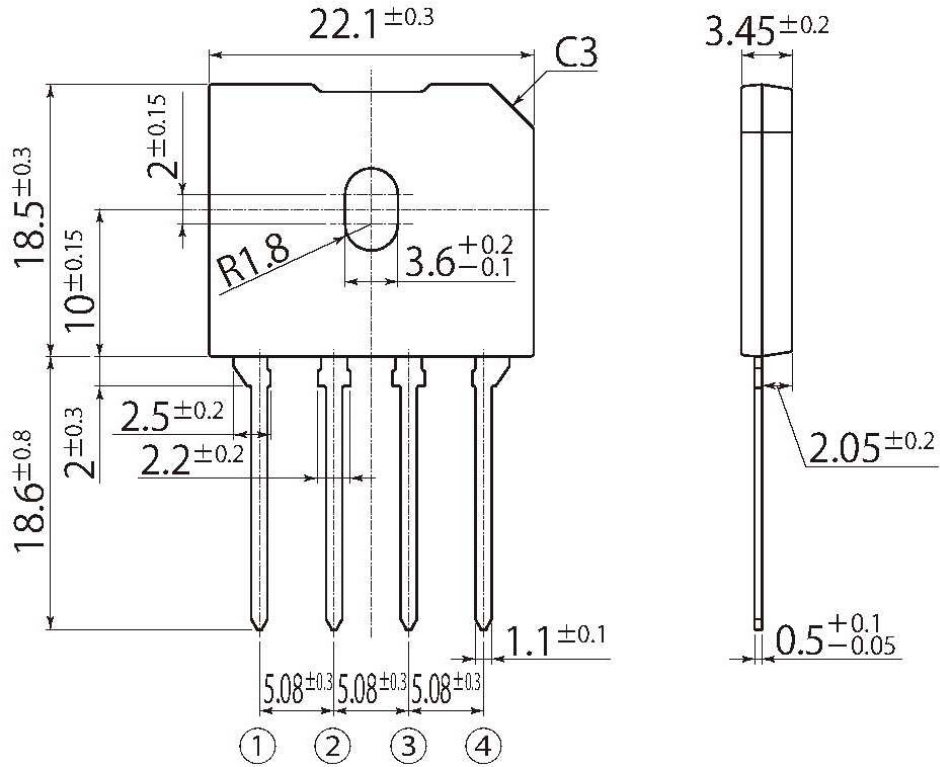
Type	Glass-epoxy
Size	90mm × 150mm
Thickness	1mm
Conductor thickness	35μm
Pattern area	160mm ²

● TI sensing point



D11

JEDEC Code	—
JEITA Code	—
House Name	D6K



Notes

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